

## CLAIMS

1. A laminated ceramic electronic part comprising:

a plurality of ceramic sheets, each having an internal conductor pattern containing a first land at one end of the internal conductor pattern and a second land at the other end and having a via hole formed therein, the plurality of ceramic sheets being laminated to constitute a laminate,

wherein the via hole is filled with a conductive material,

wherein the internal conductor patterns disposed on different layers are electrically connected to each other through the via hole,

wherein the first land is contained so as to cover the via hole and the first land contained in one ceramic sheet is electrically connected to the second land contained in another ceramic sheet through the via hole contained in the one ceramic sheet, and

wherein the second land is larger than the first land.

2. A laminated ceramic electronic part as claimed in claim 1, wherein the second land is extended from a projection plane of the first land to a projection plane of the coil conductor pattern.

3. A laminated ceramic electronic part as claimed in claim 1 or 2, wherein the area of the second land is 1.10 to 2.25 times as wide as the area of the first land.

4. A manufacturing method for a laminated ceramic electronic part, comprising the steps of:

printing an internal conductor pattern having a first land at one end of the internal conductor pattern and a second land at the other end on the surface of a ceramic sheet having a hole for via hole formed therein by using a conductive material in such a way that the first land covers the hole for via hole,

filling the conductive material in the hole for via hole,  
and

laminating a plurality of ceramic sheets in such a way that the first land contained in one ceramic sheet is electrically connected to the second land contained in another ceramic sheet through the via hole contained in the one ceramic sheet to obtain a laminate,

wherein the second land is larger than the first land.

5. A manufacturing method for a laminated ceramic electronic part as claimed in claim 4, wherein the second land is extended from a projection plane of the first land to a projection plane of the coil conductor pattern.

6. A manufacturing method for a laminated ceramic electronic part as claimed in claim 4 or 5, wherein the area of the second land is 1.10 to 2.25 times as wide as the area of the first land.

7. A manufacturing method for a laminated ceramic electronic part as claimed in any one of claims 4 to 6, wherein the internal conductor pattern is printed on a ceramic sheet having the hole for via hole formed therein and the hole for via hole is filled with a conductive material, without making the ceramic sheet backed with a carrier film.